



UNITRIDE

Unipolar Nitride Photonic devices



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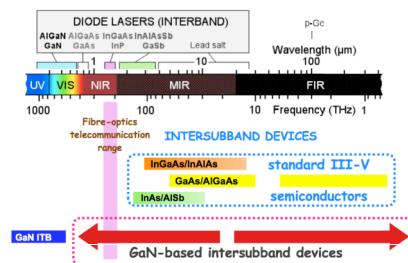
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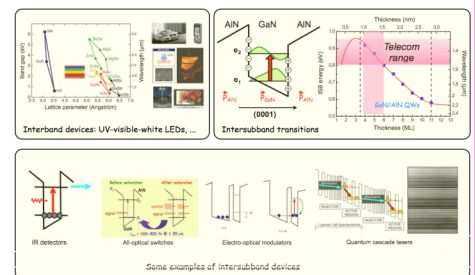
MOTIVATIONS

- Semiconductor materials can be made optically active at wavelengths regardless of their band gap by engineering the electron quantum confinement in ultrathin quantum well layers.
- A new class of optoelectronic devices can be realized with superior performances in terms of wavelength tuning, speed or optical power.
- These control-by-design devices rely on optical intersubband transitions between the electron confined states and the desired wavelength of operation can be obtained through a proper choice of the layer thicknesses.
- There is considerable interest in extending the wavelength range of intersubband devices from the near- to the far-infrared spectrum.
- As examples, high-power lasers, sensitive room-temperature detectors or ultrafast optical processing devices are highly demanded.
- Numerous appealing applications: telecommunication optoelectronic devices at optical-fiber transmission windows, chemical sensing and pollution detection, industrial process monitoring, night vision, non-invasive medical diagnostics, automotive anti-collision monitoring systems, lidars...

Why GaN-based quantum engineered devices

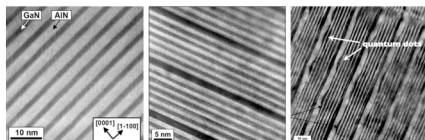


Towards III-nitride photonics from UV to THz



State-of-the-art material growth

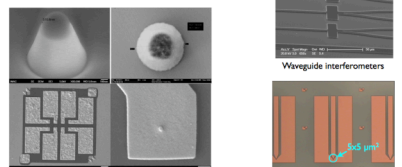
- Challenges:
 - thickness control of ultra thin layers down to one atomic monolayer.
 - high quality layers and interfaces, strain management.
- Molecular beam epitaxy using nitrogen plasma or ammonia cracking.



Transmission electron microscopic images of GaN/AlGaIn quantum well and quantum dot superlattices

Processing technology

- Challenges
 - Deep-etching of AlGaIn alloys (ICP-RIE)
 - Omic contacts
 - Micro-devices
 - Patterning low-loss waveguides



Nano-diodes with 300 nm diameter

High-speed quantum cascade detectors

Electro-optical modulators

- Amplitude modulators at 1.3-1.55 μm wavelength

